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IN THE SPECIFICATION

Please replace the fourth paragraph on Page 21, beginning at line 20, with the following paragraph.

Specifically, as shown in FIG. 28, when the lead frame 1 and the heat sink 5 are clamped with upper and lower dies 15 and 16 of a molding die in the resin molding step, the back surface 1g of each of the outer leads 1b and the back surface 5b of the heat sink 5 should be clamped together by the examping clamping surface 16a of the lower die 16 by using the clamping surface 15a of the upper die 15 as a mold reference (P). At this time, if a space is formed between the clamping surface 16a and the back surface 1g of the outer lead 1b or between a cavity surface 16b and the back surface 5b of the heat sink 5, the resin burr 14 on the surface of the outer lead or the resin burr 14 on the back surface of the heat sink shown in FIGS. 26 and 27 illustrating the comparative examples occur. The resin burr 14 is a thin-film burr on the micron order.